

	L #	Hits	Search Text	DBs	Time Stamp
1	L1	0	scarificial adj(base core substrate workpiece piece object)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/05 10:27
2	L2	391	sacrificial adj(base core substrate workpiece piece object)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/05 10:29
3	L3	10	<i>HIP, hot pressing</i> 2 and <u>isostatic</u> \$5 adj press\$4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/05 10:30

L4 (29) 2 + ((not heat\$4) adj press\$4 or HIP) not 3
L5 (3) 2 P(metallurgic\$5 adj Berol\$4) not (3 core)

SN09/817, 757

C3

	Document ID	Issue Date	Title	Current OR	Inventor
1	US 200300273 73 A1	20030206	Methods for providing void-free layers for semiconductor assemblies	438/106	DiStefano, Thomas H. et al.
2	US 200201368 40 A1 <i>09/817,757</i>	20020926	Corrosion resistant component and method for fabricating same	427/446	Hebeisen, John C. et al.
3	US 200200946 71 A1	20020718	Methods for providing void-free layers for semiconductor assemblies	438/612	Distefano, Thomas H. et al.
4	US 6458681 B1	20021001	Method for providing void free layer for semiconductor assemblies	438/612	DiStefano, Thomas H. et al.
5	US 6107123 A	20000822	Methods for providing void-free layers for semiconductor assemblies	438/125	Distefano, Thomas H. et al.

	Document ID	Issue Date	Title	Current OR	Inventor
6	US 5834339 A	19981110	Methods for providing void-free layers for semiconductor assemblies	438/125	Distefano, Thomas H. et al.
(B16)	US 5822853 A	19981020	Method for making cylindrical structure with cooling channels	29/890.01	Ritter, Ann Melinda et al.
(D23)	US 5206083 A	19930427	Diamond and diamond-like films and coatings prepared by deposition on substrate that contain a dispersion of diamond particles	428/323	Raj, Rishi et al.
(D24)	US 5183602 A	19930202	Infra red diamond composite	252/587	Raj, Rishi et al.

	Document ID	Issue Date	Title	Current OR	Inventor
10	HIP Abstract US 4370789 A <i>turning of Cu by coating with HIP</i>	19830201	Fabrication of gas turbine water-cooled composite nozzle and bucket hardware employing plasma spray process	29/889.72 2	Schilke, Peter W. et al.

L4

#10 6,549,700 Sweett et al
See Fig. 8 + (D27) In Fig 8... core suspension 53 similar to sacrificial sub-
(D28)..
Jumbo + poor

#16 6,336,269 Eldridge et al
Fig 11, dec. (D459-468) - sacrificial sub 1104
+ multi layer, burn no
encapsulation

no coat
poor

#27 4,344,134 Hiltner
Fig 1, 2, 3, 5-17 - sacrificial core portion
(D1) Turning to Fig. 1 low density sacrificial portion 16 - temp. sustained
(D3) Subsequent to achievement assembly of thermocouples w/ "bagged" ceramic
w/ heat & pressure → disassembly & 16 removed by pulling away attachment

LS

5

	Document ID	Issue Date	Title	Current OR	Inventor
1	US 6229100 B1 (B12) mech press rather than mechanical tool	20010508	Low profile socket for microelec tronic component s and method for making the same	174/261	Fjelstad, Joseph
2	US 6060341 A	20000509	Method of making an electroni c package	438/123	Alcoe, David James et al.
3	US 5983492 A	19991116	Low profile socket for microelec tronic component s and method for making the same	29/843	Fjelstad, Joseph